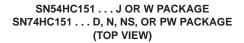
SCLS110E – DECEMBER 1982 – REVISED SEPTEMBER 2003

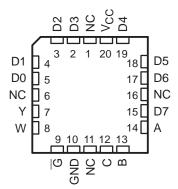
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 13 ns
- ±6-mA Output Drive at 5 V



	Г		U		L	
D3	Цí			16	μ	V _{CC}
D2		2		15		D4
D1	[3	3		14		D5
D0	[]	1		13		D6
Y	[5		12		D7
W	[] (6		11		А
G	[7	7		10		В
GND	Įε	3		9		С

- Low Input Current of 1 μA Max
- 8-Line to 1-Line Multiplexers Can Perform as:
 - Boolean-Function Generators
 - Parallel-to-Serial Converters
 - Data Source Selectors





NC - No internal connection

description/ordering information

These data selectors/multiplexers provide full binary decoding to select one of eight data sources. The strobe (\overline{G}) input must be at a low logic level to enable the inputs. A high level at the strobe terminal forces the W output high and the Y output low.

T _A	PACKA	GEŤ	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HC151N	SN74HC151N
		Tube of 40	SN74HC151D	
	SOIC – D	Reel of 2500	SN74HC151DR	HC151
–40°C to 85°C		Reel of 250	SN74HC151DT	
-40°C to 85°C	SOP – NS	Reel of 2000	SN74HC151NSR	HC151
		Tube of 90	SN74HC151PW	
	TSSOP – PW	Reel of 2000	SN74HC151PWR	HC151
		Reel of 250	SN74HC151PWT	
	CDIP – J	Tube of 25	SNJ54HC151J	SNJ54HC151J
–55°C to 125°C	CFP – W	Tube of 150	SNJ54HC151W	SNJ54HC151W
	LCCC – FK	Tube of 55	SNJ54HC151FK	SNJ54HC151FK

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 2003, Texas Instruments Incorporated On products compliant to MIL-PRF-3853s, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

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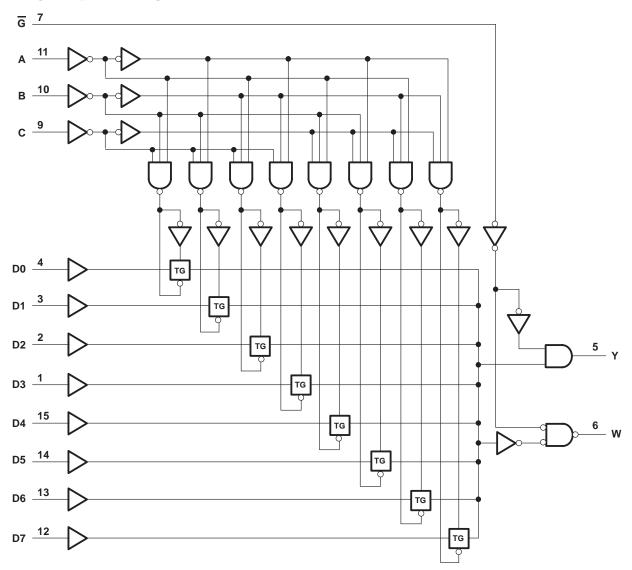
	STROBE Y W A G Y W X H L H L L D0 D0 H L D1 D1 L L D2 D2 H L D3 D3 L L D4 D4			
IN	IPUTS		OUTI	PUTS
BELECT			v	14/
В	Α	G	Y	vv
Х	Х	Н	L	Н
L	L	L	D0	D0
L	Н	L	D1	D1
Н	L	L	D2	D2
Н	Н	L	D3	D3
L	L	L	D4	D4
L	Н	L	D5	D5
Н	L	L	D6	D6
Н	Н	L	D7	D7
	B B X L L H H L L H H	INPUTS B A X X L L L H H L H H H H H L H H H H H H H H H H H H	INPUTS SELECT STROBE B A G X X H L L L L H L H L L H H L L L H H L H L	INPUTS OUTF SELECT STROBE G Y B A G Y X X H L L L L D0 L H L D1 H L L D2 H H L D3 L L L D5 H L L D6 H H L D7

D0, D1 . . . D7 = the level of the respective D input



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logic diagram (positive logic)



Pin numbers shown are for the D, J, N, NS, PW, and W packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$ Continuous output current, I_O ($V_O = 0$ to V_{CC})	ee Note 1)	±20 mA ±20 mA ±35 mA
Continuous current through V_{CC} or GND Package thermal impedance, θ_{JA} (see Note 2):		
	N package	
	NS package	64°C/W
	PW package	108°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN	154HC15	51	SN	74HC15	51	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		2	5	6	2	5	6	V
		$V_{CC} = 2 V$	1.5			1.5			
VIH	High-level input voltage	$V_{CC} = 4.5 V$	3.15			3.15		V	V
		V _{CC} = 6 V	4.2			4.2			
	$V_{CC} = 2 V$				0.5			0.5	
VIL	VIL Low-level input voltage	V _{CC} = 4.5 V			1.35			1.35	V
		V _{CC} = 6 V			1.8			1.8	
VI	Input voltage		0		VCC	0		VCC	V
VO	Output voltage		0		VCC	0		VCC	V
		$V_{CC} = 2 V$			1000			1000	
$\Delta t/\Delta v$	Input transition rise/fall time	$V_{CC} = 4.5 V$			500			500	ns
		V _{CC} = 6 V			400			400	
ТА	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				Т	A = 25°C	;	SN54H	IC151	SN74H	C151	LINUT
PARAMETER	TEST CO	NDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4		
VOH	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		I _{OH} = -6 mA	4.5 V	3.98	4.3		3.7		3.84		
		I _{OH} = -7.8 mA	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
VOL	VI = VIH or VIL		6 V		0.001	0.1		0.1		0.1	V
		I _{OL} = 6 mA	4.5 V		0.17	0.26		0.4		0.33	
		I _{OL} = 7.8 mA	6 V		0.15	0.26		0.4		0.33	
lı	$V_I = V_{CC} \text{ or } 0$		6 V		±0.1	±100		±1000		±1000	nA
ICC	$V_I = V_{CC} \text{ or } 0,$	IO = 0	6 V			8		160		80	μΑ
Ci			2 V to 6 V		3	10		10		10	pF

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то		Τį	₄ = 25°C	;	SN54H	IC151	SN74H	IC151	LINUT
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		94	250		360		312	
	A, B, or C	Y or W	4.5 V		30	50		73		63	
			6 V		25	43		62		54	
			2 V		74	195		283		244	
^t pd	Any D	Y or W	4.5 V		23	39		57		49	ns
			6 V		20	33		48		41	
			2 V		49	127		185		159	
	G	Y or W	4.5 V		15	25		37		32	
			6 V		13	22		32		28	
			2 V		22	75		110		95	
t		Y or W	4.5 V		9	15		22		19	ns
			6 V		8	13		19		16	



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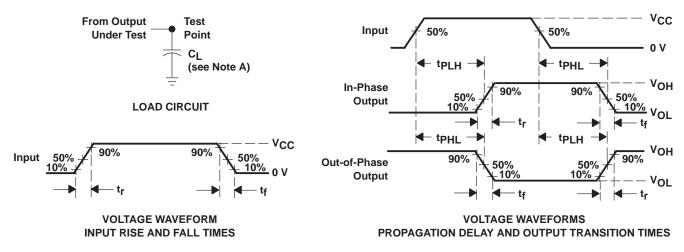
switching characteristics over recommended operating free-air temperature range, $C_L = 150 \text{ pF}$ (unless otherwise noted) (see Figure 1)

	FROM	то		Тд	√ = 25°C	;	SN54H	IC151	SN74H	IC151		
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
			2 V		107	350		525		440		
	A, B, or C	Y or W	4.5 V		33	70		105		88	3	
			6 V		30	59		89		76		
			2 V		90	275		415		345		
^t pd	Any D	Y or W	4.5 V		29	51		83		69) ns	
·			6 V		25	47		72		59		
			2 V		67	205		310		255		
	G	Y or W	4.5 V		21	41		62		51		
			6 V		18	35		53		43		
			2 V		51	210		315		265		
tt		Y or W	4.5 V		16	42		63		53	ns	
			6 V		14	36		53		45		

operating characteristics, T_A = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
Cpd	Power dissipation capacitance	No load	70	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. CL includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_f = 6 ns, t_f = 6 ns.
- C. The outputs are measured one at a time with one input transition per measurement.
- D. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms





10-Jun-2014

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
84128012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84128012A SNJ54HC 151FK	Samples
8412801EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8412801EA SNJ54HC151J	Samples
SN54HC151J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54HC151J	Samples
SN74HC151D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC151	Samples
SN74HC151DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC151	Samples
SN74HC151DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC151	Samples
SN74HC151DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC151	Samples
SN74HC151DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC151	Samples
SN74HC151DT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC151	Samples
SN74HC151N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC151N	Samples
SN74HC151NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC151	Samples
SN74HC151PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC151	Samples
SN74HC151PWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC151	Samples
SN74HC151PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC151	Samples
SN74HC151PWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC151	Samples
SNJ54HC151FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84128012A SNJ54HC 151FK	Samples



10-Jun-2014

Orderable Device	Status	Package Typ	e Package	Pins	•	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SNJ54HC151J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8412801EA SNJ54HC151J	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54HC151, SN74HC151 :



PACKAGE OPTION ADDENDUM

10-Jun-2014

Catalog: SN74HC151

• Automotive: SN74HC151-Q1, SN74HC151-Q1

Military: SN54HC151

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com

Texas Instruments

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC151DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC151PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC151PWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

8-Apr-2013



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC151DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74HC151PWR	TSSOP	PW	16	2000	367.0	367.0	35.0
SN74HC151PWT	TSSOP	PW	16	250	367.0	367.0	35.0

J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES:

A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994. β . This drawing is subject to change without notice.

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

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